



Material Content Data Sheet



Sales Product Name				BSZ120P03NS3 G		Issued		20. July 2018	
MA#				MA001321032					
Package				PG-TSDSON-8-2		Weight*		38.42 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.346	3.50	3.50	35025	35025	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55		
	non noble metal	zinc	7440-66-6	0.008	0.02		218		
	non noble metal	iron	7439-89-6	0.168	0.44		4364		
wire	non noble metal	copper	7440-50-8	6.808	17.72	18.19	177201	181838	
	non noble metal	copper	7440-50-8	0.050	0.13	0.13	1309	1309	
	organic material	carbon black	1333-86-4	0.035	0.09		901		
encapsulation	plastics	epoxy resin	-	1.783	4.64		46416		
	inorganic material	silicondioxide	60676-86-0	15.495	40.34	45.07	403327	450644	
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10077	10077	
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25056	25056	
solder	noble metal	silver	7440-22-4	0.037	0.10		972		
	non noble metal	tin	7440-31-5	0.030	0.08		777		
	non noble metal	lead	7439-92-1	1.426	3.71	3.89	37123	38872	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28		
	non noble metal	zinc	7440-66-6	0.004	0.01		112		
	non noble metal	iron	7439-89-6	0.086	0.22		2244		
	non noble metal	copper	7440-50-8	3.501	9.11	9.34	91134	93518	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49		
	non noble metal	zinc	7440-66-6	0.008	0.02		196		
	non noble metal	iron	7439-89-6	0.151	0.39		3928		
	non noble metal	copper	7440-50-8	6.127	15.95	16.36	159488	163661	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com